

Samsung Class100 eMCP Solution

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Memory Sales & Marketing

Samsung Memory

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Intro



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What is eMCP?

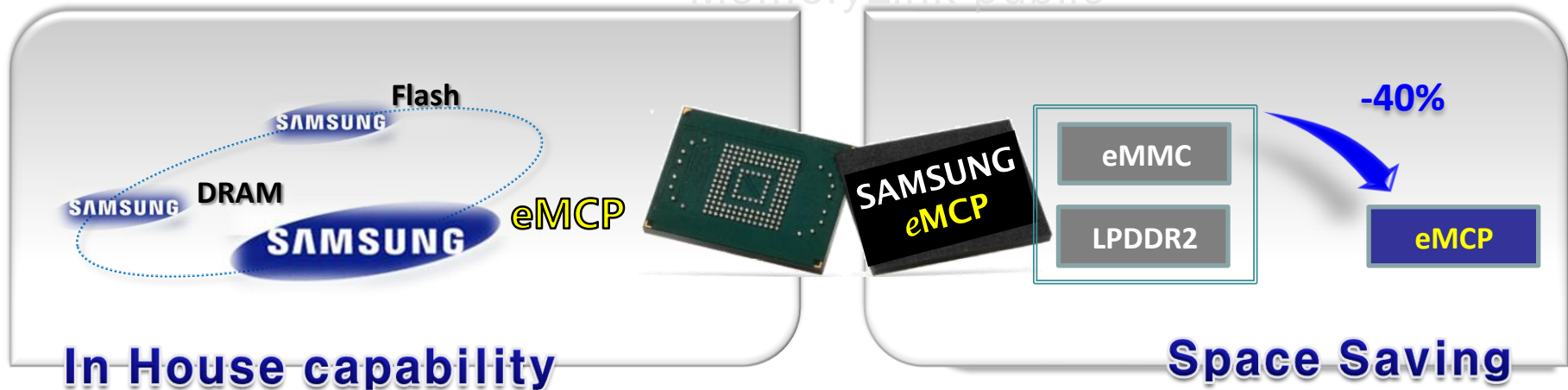
■ eMCP : Multi-Chip Package with eMMC

■ Why Samsung eMCP?

- Combine ROM and RAM : Single supplier (Samsung Flash, Samsung DRAM)
- Small Space needed : Save up to 40% of space on memory b'd

■ Which eMCP adoptable for Set Makers

- ME : eMMC + LPDDR2 DRAM
- MD : eMMC + LPDDR1 DRAM
- Both chipsets that can support LPDDR1 and LPDDR2 can use Samsung eMCP by Full Line-up support



■ What is Class ?

- **Samsung eMMC Line-up naming based on 'Random write IOPS'**
- **Random IOPS is KEY factor for system memory operation**
- **Samsung Test Condition**

| Pre-condition | Test Environment & methodology |
|-----------------|--|
| Dirty Condition | 1) Platform : eMMC device level, x8 bus width, 50MHz DDR 2) Random read/write Chunk size : 4KB*, Total I/O (1GB, 1GB range) |

* 4KB data chunk size is file system meta size and main chunk size for operating system

■ Suitable solution for each Segmentation (12' Q4~13'1H Model)

| Item | Class100 | Class400 | Class1500 | Class2000 |
|------------------------------|-------------------------|--------------------------------|--|---------------------|
| Smart Phone Segment | ULC | Low-end | Mid-range | High-end (Flagship) |
| | Single Core | Dual Core | Quad Core | |
| Major Functions (Example) | Basic Operation | Gaming, Multi-tasking, etc. | Burst shooting with high quality pixel, 3D Multimedia playing, etc. | |
| OS Requirement | Android*, Windows Phone | | Android*, Windows Phone, Window8 | |

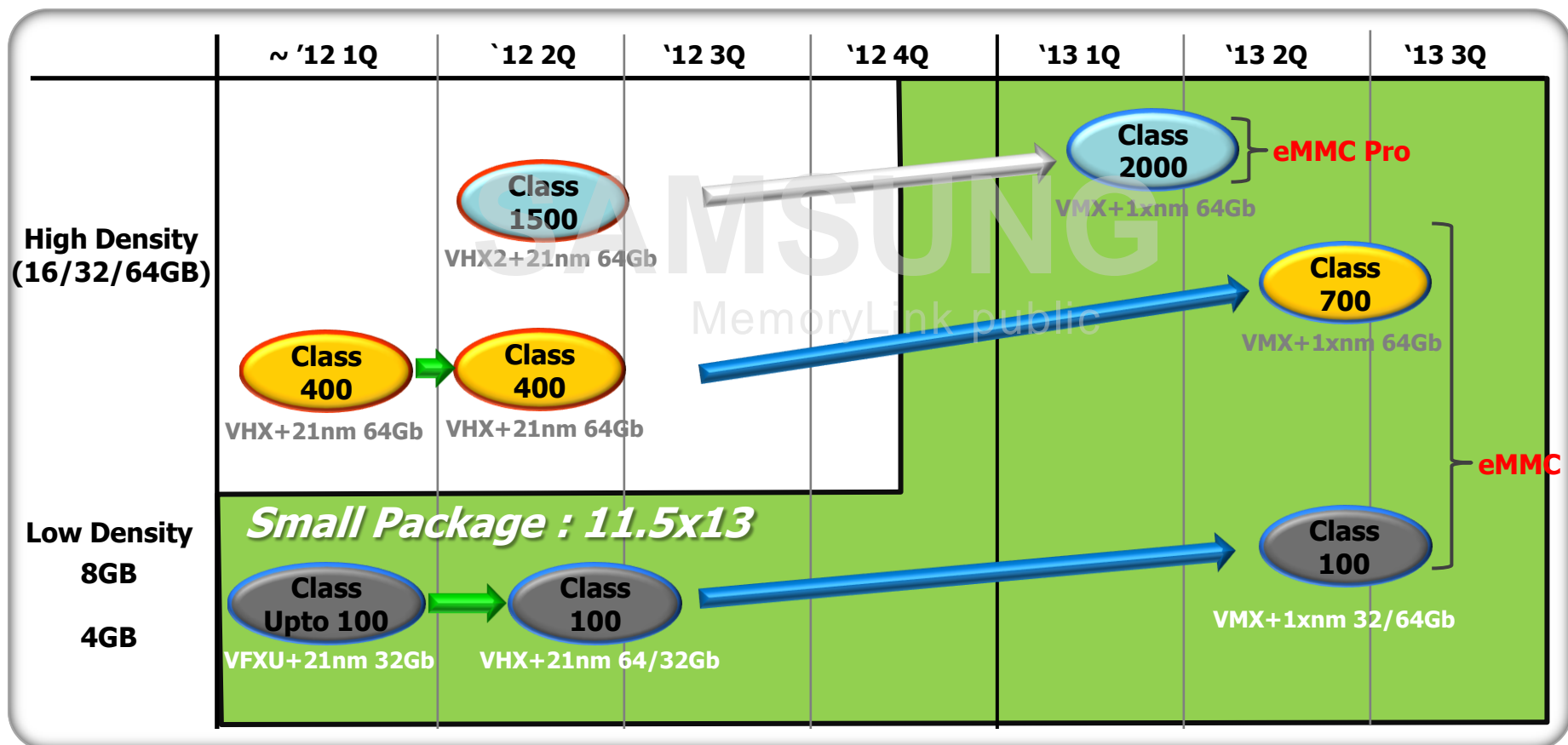
* Android doesn't have special specification for Memory

Samsung eMCP Class Roadmap

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■ Samsung has wide range of eMMC solution based on performance requirements

- eMMC for Low-end to High-end with Class 100 to Class 700
- eMMC Pro for Flagship/Win8 PJT with Class 1500 to Class 2000



Class100 eMCP Introduction

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Line-up



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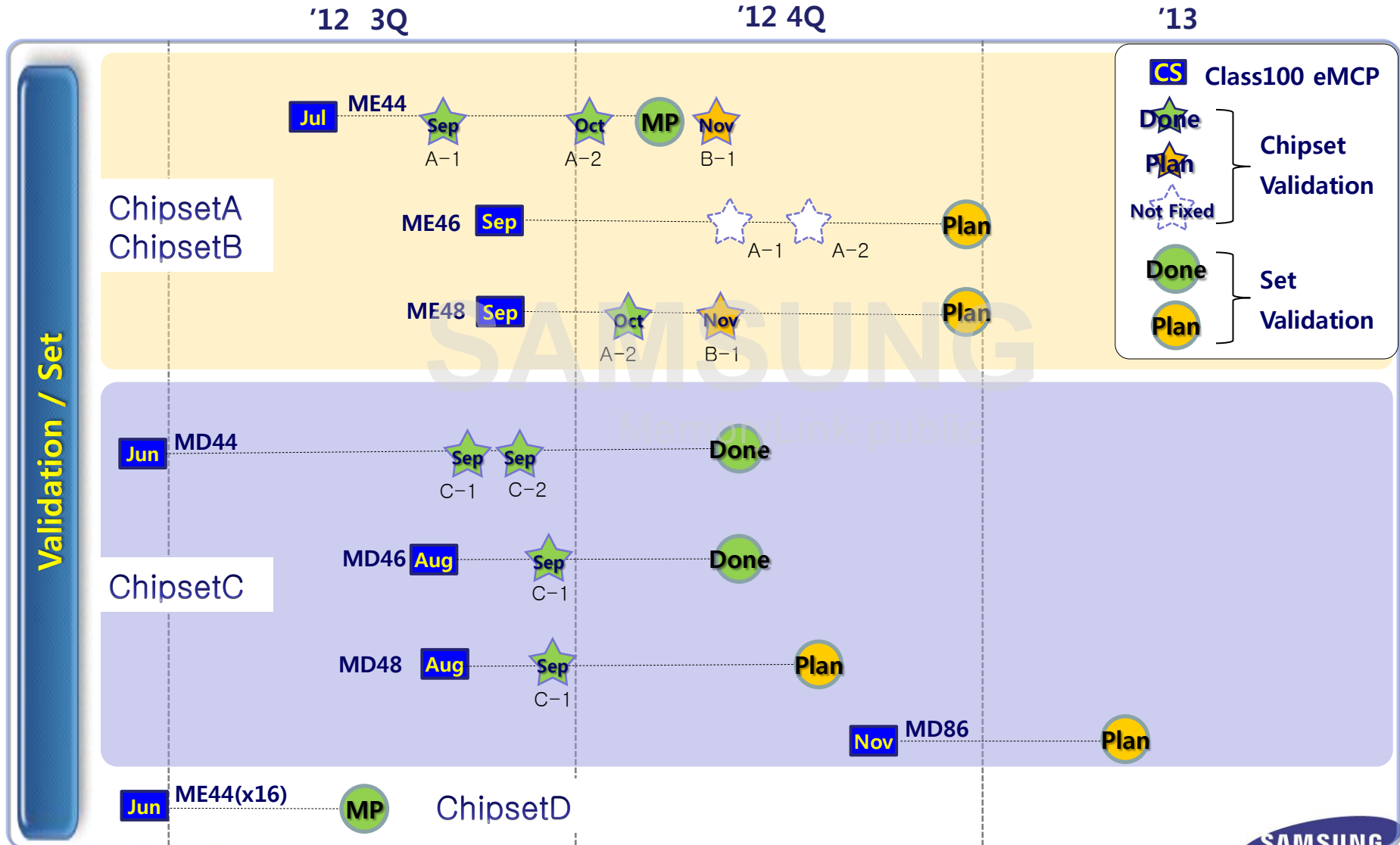
Samsung Class100 eMCP Line-up



| IF | eMCP | Package | Part# | Patch | Status | Validation on Chipset |
|--------------|----------------|----------------------|-----------------|-------|---------------|-----------------------|
| MDDR based | MD4GB_4G | 153B, 11.5x13x1.0mmt | KMS5U000KM-B308 | 02 | CS | Done |
| | MD4GB_6G | 153B, 11.5x13x1.0mmt | KMJ5U000WA-B409 | 02 | CS | Done |
| | MD4GB_8G | 153B, 11.5x13x1.2mmt | KML5U000HM-B505 | 02 | CS | Done |
| | MD8GB_6G | 153B, 11.5x13x1.2mmt | | 02 | CS : Nov. '12 | (Not Planned Yet) |
| LPDDR2 based | ME4GB_4G (x16) | 162B, 11.5x13x1.0mmt | KMN5U000FM-B203 | 00 | MP | Done |
| | ME4GB_4G (x32) | 162B, 11.5x13x1.0mmt | KMN5U000ZM-B203 | 02 | MP | Done |
| | ME4GB_6G (x32) | 162B, 11.5x13x1.0mmt | KMK5U000YM-B309 | 02 | CS | (Not Planned Yet) |
| | ME4GB_8G (x32) | 162B, 11.5x13x1.0mmt | KMK5U000VM-B309 | 02 | CS | Done |
| | ME8GB_8G (x32) | 162B, 11.5x13x1.0mmt | - | - | CS : Feb. '12 | (Not Planned Yet) |

Samsung Class100 Validation Status

- Class100 eMCP is validated by Chipset and Set Makers



Smart Phone with eMMC Class100



■ ICS Smart Phone MP with eMCP ME4GB4G(eMMC Class100)

Galaxy Chat Specifications

| | |
|------------|--|
| Maker | Samsung Mobile |
| Chipset | BCM21654 |
| OS | Android 4.0 ICS |
| DRAM | <u>Samsung eMCP ME4G4G</u> <u>(Samsung eMMC Class100 4GB)</u> |
| Flash | |
| LCD Size | 3.0 Inch |
| Resolution | QVGA(240X320), 2MPixel |
| Launching | '12 July |

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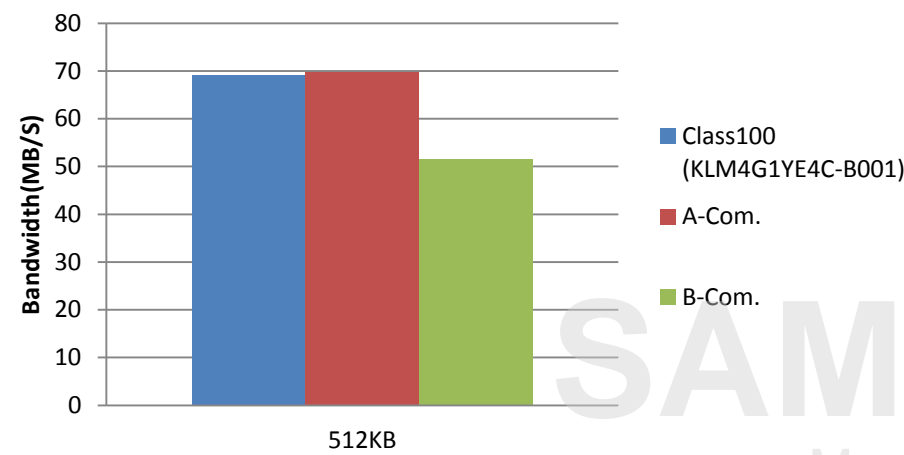
Performance



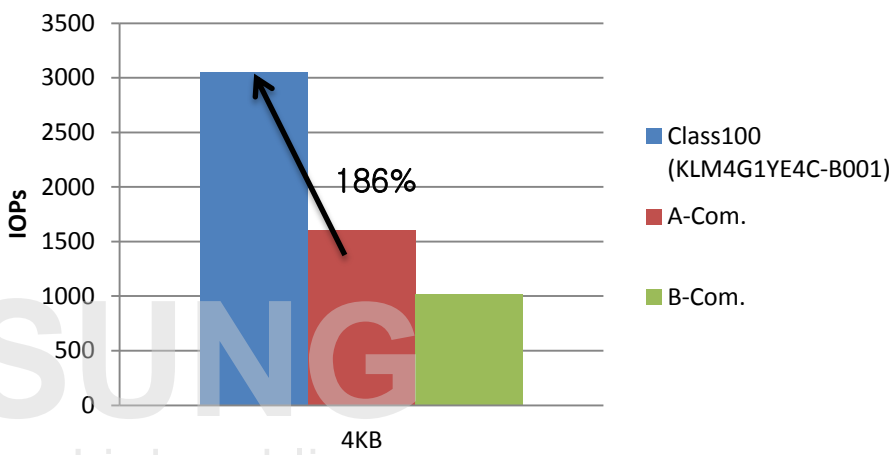
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■ Class100 has competitive edge comparing to others

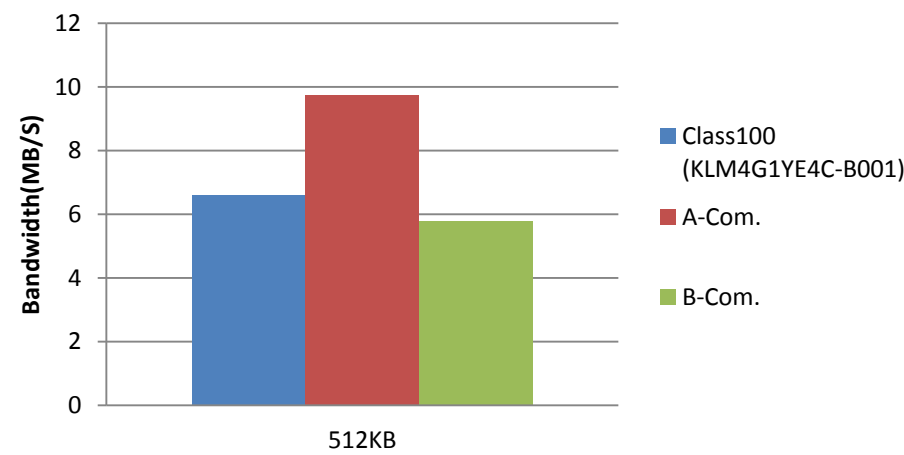
Seq. Read



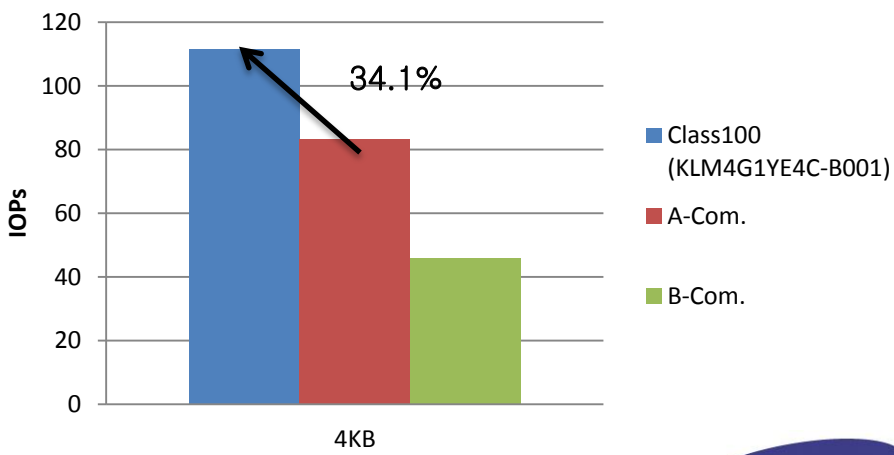
Rand. Read



Seq. Write



Rand. Write



Set Level Performance Comparison Result



■ Test Condition

| | AP | Memory | OS |
|----------------------|--------------|-----------------|-----------|
| A Smart Phone | A-CPU | MD4GB4Gb | GB |

■ Test Result

| | Test Item | Description | `11Year [sec] | `12Year [sec] | Performance Gap | Test Environment |
|---|-----------------|---|------------------|------------------|--------------------|------------------|
| Performance Clean Precondition | File copy Write | Small file copy(Sec) Write (PC → eMMC) | 47.2 | 29.6 | 37.3% | 225MB |
| | | Big file copy(Sec) Write (PC → eMMC) | 49.6 | 33.0 | 33.5% | 316MB |
| | File copy Read | Small file copy(Sec) Read (eMMC → PC) | 21.2 | 19.4 | 8.5% | 225MB |
| | | Big file copy(Sec) Read (eMMC → PC) | 22.7 | 23.4 | -3.1% | 316MB |
| | App | Application install(Sec) | 22.9 | 15.8 | 31.0% | 101MB |

| | | | | | | |
|---|-----------------|---|------|------|---------------|-------|
| Performance Dirty Precondition (62 % Filled) 600MB remained | File copy Write | Small file copy(Sec) Write (PC → eMMC) | 55.1 | 56.3 | -2.2% | 225MB |
| | | Big file copy(Sec) Write (PC → eMMC) | 63.9 | 57.0 | 10.8% | 316MB |
| | File copy Read | Small file copy(Sec) Read (eMMC → PC) | 16.4 | 14.8 | 9.8% | 225MB |
| | | Big file copy(Sec) Read (eMMC → PC) | 16.4 | 18.3 | -11.6% | 316MB |
| | App | Application install(Sec) | 52.8 | 49.9 | 5.5% | 101MB |

Set Level Performance Comparison Result



■ Test Condition

| | AP | Memory | OS |
|----------------------|--------------|-----------------|------------|
| A Smart Phone | B-CPU | ME4GB4Gb | ICS |

■ Test Result

| | Test Item | Description | `11Year [sec] | `12Year [sec] | Performance Gap | Test Environment |
|---|-----------------|---|------------------|------------------|--------------------|------------------|
| Performance Clean Precondition | File copy Write | Small file copy(Sec) Write (PC → eMMC) | 43.7 | 36.0 | 17.6% | 225MB |
| | | Big file copy(Sec) Write (PC → eMMC) | 41.8 | 37.3 | 10.8% | 316MB |
| | File copy Read | Small file copy(Sec) Read (eMMC → PC) | 33.4 | 29.9 | 10.3% | 225MB |
| | | Big file copy(Sec) Read (eMMC → PC) | 30.2 | 27.2 | 9.8% | 316MB |
| | App | Application install(Sec) | 25.2 | 14.0 | 44.5% | 101MB |

| | | | | | | |
|---|-----------------|---|------|------|---------------|------------------------|
| Performance Dirty Precondition (62 % Filled) 600MB remained | File copy Write | Small file copy(Sec) Write (PC → eMMC) | 43.9 | 39.4 | 10.3% | 225MB |
| | | Big file copy(Sec) Write (PC → eMMC) | 44.1 | 44.4 | - 0.8% | 316MB |
| | File copy Read | Small file copy(Sec) Read (eMMC → PC) | 33.2 | 29.9 | 9.9% | 225MB |
| | | Big file copy(Sec) Read (eMMC → PC) | 29.6 | 27.9 | 5.7% | 316MB |
| | App | Application install(Sec) | 22.5 | 15.5 | 31.1% | Racing Game (101MB) |

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Endurance



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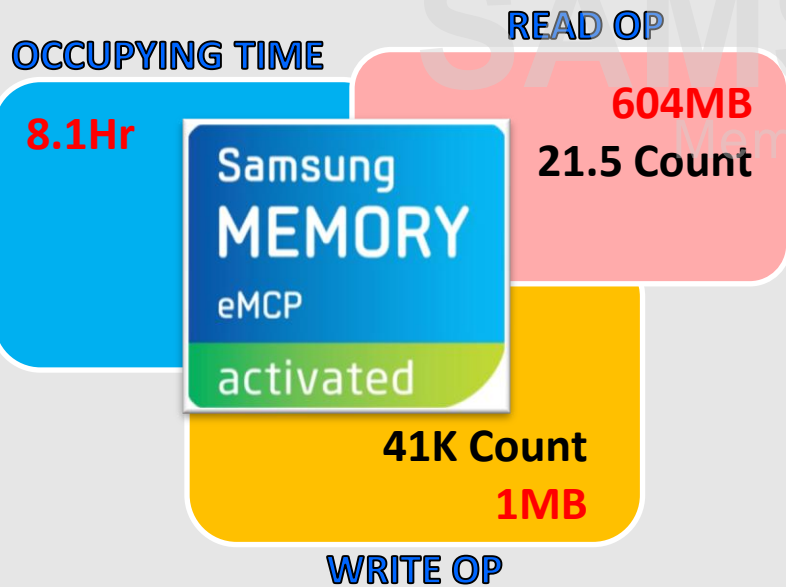
User Scenario base Life Time of 4GB Class100

- Class100 eMCP can Endure for 3years following Simulation
 - User Scenario

Simulation Result

4.6yr Life time for Heavy User (1MB/day write)

[User Scenario from SetMakerA]

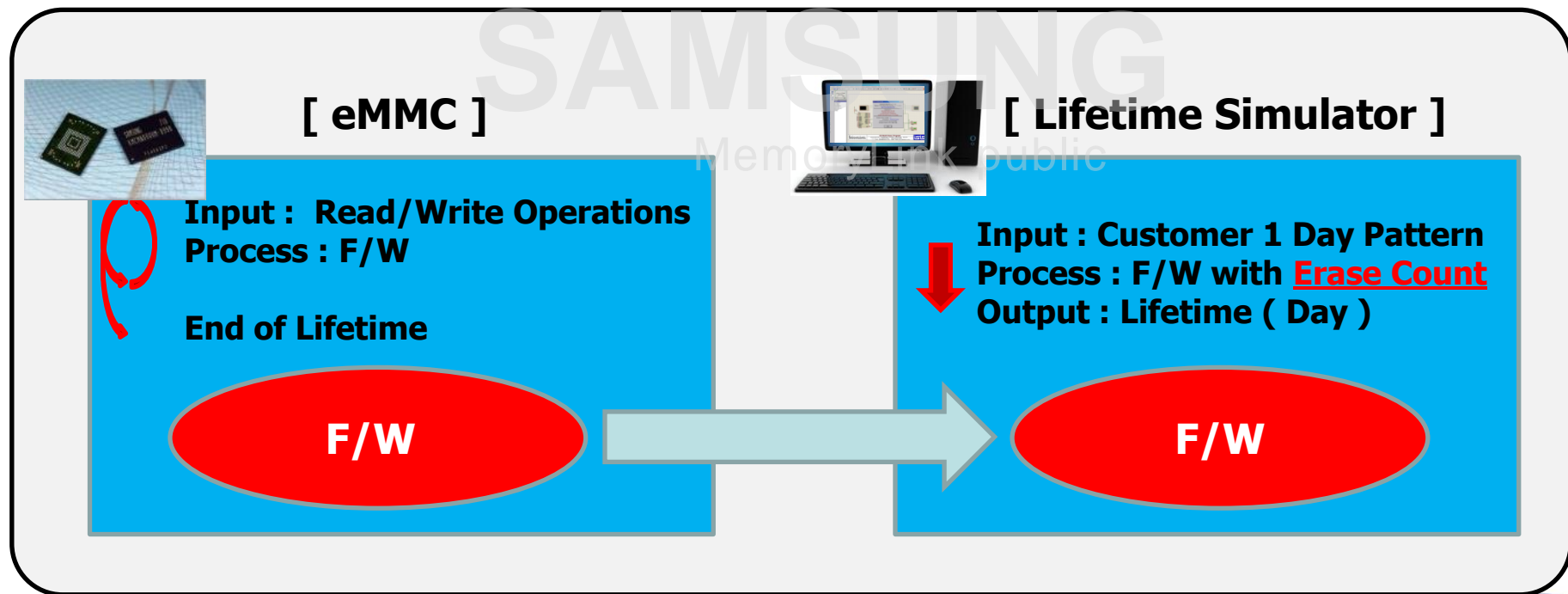


Samsung Class 100 guarantee a life of almost **3 years**

If the user scenario is much more severe or critical in nature, contact SEC HQ with respective scenario.

How to Simulate Lifetime

- Life time estimation of eMMC could be using Lifetime Simulator
- Simulator expects a day's work load pattern.
 - Lifetime of a third party vendor device cannot be simulated.
 - No Simulator for Other Vendor's or No Way to Know Erase Count



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Solution for Each Display



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Memory Recommendation : LPDDR1

■ Line-up for various smart phone specification

- Without DRAM POP, eMCP will support various DRAM Density
- POP Stack Process is not needed



Memory Recommendation : LPDDR2

■ Line-up for various smart phone specification

- Without DRAM POP, eMCP will support various DRAM Density
- POP Stack Process is not needed



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Validation Result



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Chipset Joint Validation Result (Class100 + Chipset A)



- **eMCP Class100 4GB Validated on Popular platform (Chipset A)**
 - Platform Info. : Chipset A + Android 4.0(ICS)
- **By validating eMMC Class100 4GB on Chipset A, we've optimized performance related factors**

| # | Validation Item | Reference | Analysis Results | Comments |
|---|-----------------------------|------------------------------------|------------------|---|
| 1 | Basic Analysis | AC/DC parameter | No issue | - |
| | | Timing Parameter | No issue | - |
| | | Power up Cycling | No issue | - |
| | | Bootup/initialize sequence | No issue | Unnecessary CMD optimization |
| | | Transfer Mode check (R/W function) | No issue | Address misalign, chunk size optimization done |
| 2 | Performance Analysis | B/M Tool Test | No issue | Address discontinuity, chunk size optimization done |
| | | User Scenario performance test | No issue | |
| 3 | SI/PI Management | SI Check | No issue | - |
| | | PI Check | No issue | - |

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Contact US



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Contact for More about Class100



■ Contact window (@China region & Korea)

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Thank you



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